



Material Content Data Sheet



Sales Product Name	TLE7233EM			Issued	4. July 2019			
MA#	MA005344681							
Package	PG-SSOP-24-4			Weight*	150.34 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.861	1.24	1.24	12377	12377
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		112	
	non noble metal	zinc	7440-66-6	0.067	0.04		447	
	non noble metal	iron	7439-89-6	1.345	0.89		8947	
wire	non noble metal	copper	7440-50-8	54.617	36.33	37.27	363294	372800
	noble metal	gold	7440-57-5	0.515	0.34	0.34	3425	3425
	encapsulation	organic material	carbon black	1333-86-4	0.176	0.12		1172
encapsulation	plastics	epoxy resin	-	8.105	5.39		53912	
	inorganic material	silicondioxide	60676-86-0	79.818	53.09	58.60	530918	586002
leadfinish	non noble metal	tin	7440-31-5	2.911	1.94	1.94	19362	19362
plating	noble metal	silver	7440-22-4	0.234	0.16	0.16	1558	1558
glue	plastics	epoxy resin	-	0.168	0.11		1119	
	noble metal	silver	7440-22-4	0.505	0.34	0.45	3357	4476
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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